



HyperTransport™ Technology Consortium

“Here and Now!”

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Briefing Agenda

- ☐ **HyperTransport™ : “Here and Now!”**
 - Technology backgrounder
 - Enabling future I/O technologies
- ☐ **HyperTransport Technology Consortium overview**
- ☐ **New members announced**
- ☐ **HyperTransport applications**
 - Computer, communications, and embedded applications
 - Products available today
- ☐ **Developing future specifications & new markets**
- ☐ **Summary**

HyperTransport: Here and Now!



- ❑ **HyperTransport™ technology improves overall system performance**
 - High-speed, high performance, point-to-point link for ICs
 - Enables chips inside PCs, networking and communications devices to communicate up to 48 times faster than some existing bus technologies
 - Provides 12.8 G byte/sec total bandwidth
- ❑ **HyperTransport buses have two unidirectional links**
 - Links can be 2-,4-,8-,16- or 32-bits wide in each direction
- ❑ **Products shipping now**

Enabling Future Technologies

- ❑ **Provides designers with clear, reliable upgrade path**
 - Supports existing PCI, AGP, 1394, USB 2.0, and 1Gigabit Ethernet bus interfaces
- ❑ **High-speed, low pin-count interconnect for emerging I/O connections**
 - PCI-X, PCI 3.0
 - InfiniBand
 - South Bridge
 - AGP 8x
 - 10Gigabit Ethernet

Consortium Background



- ❑ HyperTransport™ Technology Consortium launched July 2001
- ❑ Members represent the networking, telecommunications and computer industries
- ❑ HyperTransport Technology Consortium Promoters:



HyperTransport Consortium's Goals



- ☐ **Promote the adoption of HyperTransport™ technology as a “free” industry interconnect standard**
- ☐ **Drive the expansion of a HyperTransport infrastructure to benefit the companies who incorporate it**
- ☐ **Evolve HyperTransport technology for new applications, emerging requirements, and future manufacturing technologies**
- ☐ **Ensure compatibility and interoperability of HyperTransport enabled devices**

HTC Welcomes New Members



ANNOUNCING 14 NEW MEMBERS:

0-In Design Automation, Acer Laboratories Inc., Altera, AMCC, Fast-Chip, Flow Engines, GDA Technologies, Josipa Company, LEDA Systems, Marvell Semiconductor, Nokia, Spinnaker Networks, Teradyne, Xilinx

- ☐ **Over 200 companies have evaluated the HyperTransport™ I/O specification**

Membership Benefits

- ❑ All members receive **Royalty-free** license to HyperTransport™ I/O technology Intellectual Property (with payment of annual dues)
- ❑ **Contributor Members**
 - May hold voting seats on Working Groups
 - May participate on Task Forces
 - Entitled to participate in Marketing events
 - Entitled to review preliminary and pre-released documents
- ❑ **Adopter Members**
 - Non-voting members
 - May participate in Task Forces

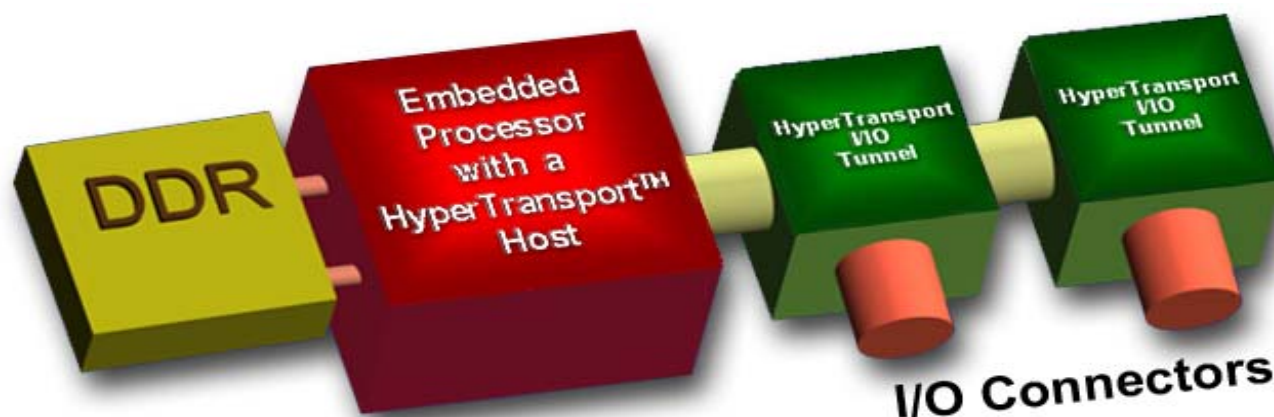
HyperTransport: Applications



- ☐ Microprocessors
- ☐ Routers
- ☐ Hubs
- ☐ Switches
- ☐ Servers
- ☐ Test equipment
- ☐ Workstations
- ☐ HDTV equipment
- ☐ PCs (desktop & notebook)
- ☐ Set-top boxes
- ☐ Mobile/handheld devices
- ☐ Game consoles
- ☐ Embedded systems

**Any Application Requiring High Speed,
Low Latency & Scalability!**

Embedded Applications and I/O Tunnels



❑ For the 1st time in the industry:

- I/O devices shared among computation and communication industry
- Unique “TUNNELING” capability designed to provide almost unlimited I/O expandability
- Fundamentally different microprocessor and memory controllers may be designed to use the very same I/O components
- Pin count adjustable for the necessary bandwidth
- Cost reduced due to the cumulative volume
- Extended component life

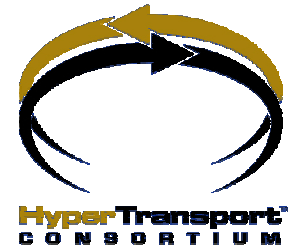
HyperTransport: Here and Now

- ☐ **PMC-Sierra announced RM9000x2™ integrated MIPS multiprocessor**
- ☐ **NVIDIA announced nForce chipset with integrated graphics**
- ☐ **Broadcom announced BCM1250 MIPS CPU**
- ☐ **API Networks introduced the industry's first HyperTransport-to-PCI bridge chip, the AP1011, and the first HyperTransport switch, AP4041**
- ☐ **AMD announced Hammer, 8th generation architecture for microprocessors**
- ☐ **Altera uses Hypertransport in APEX II devices**
- ☐ **Xilinx uses Hypertransport in Virtex®-II devices**
- ☐ **Teradyne announced HyperTransport testers**

Technical Goals

- ❑ **Manage and evolve the specifications**
 - manage incident reports, clarifications, revision control, FAQs
 - extend the feature set, as needed:
 - » error management
 - » larger address spaces
 - » coherency
 - » enhance security
- ❑ **Build the HyperTransport™ Infrastructure**
 - resources and technical libraries
 - tools, testers, diagnostics, etc.
 - licensable IP: Register Transistor Level (RTL), Physical Interfaces (PHYs), verification suites, etc.
- ❑ **Protect the investment of early adopters**
 - interoperability and backwards compatibility

“New” Market Opportunities



To augment the adoption of HyperTransport™ technology, the Consortium will promote the development of:

- A diverse mix of CPU/platform architectures
- Classifiers
- Security Chips
- TCP Termination
- 1 Gigabit / 10 Gigabit Ethernet solutions
- InfiniBand
- Connectors and cables
- Test equipment and verification tools
- Software tools and diagnostics
- EDA solutions

Summary



- ☐ **HyperTransport™ technology enables chips inside PCs, networking and communications devices to communicate with each other up to 48 times faster than some existing technologies**
- ☐ **HyperTransport Technology Consortium welcomes Broadcom and SGI as Promoter Members and an additional 14 new member companies**
- ☐ **HTC's goal is to drive the development and adoption of HyperTransport technology for current and future applications**
- ☐ **Products with HyperTransport are available and under development HERE AND NOW!**